## : ©hipsmall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation, and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!


## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email \& Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, \#122 Zhenhua RD., Futian, Shenzhen, China

## X-Class HiPERFET Power MOSFET

IXFY4N85X
IXFA4N85X IXFP4N85X


| Symbol | Test Conditions | Maximum Ratings |  |
| :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {DSs }}$ | $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$ | 850 | V |
| $\mathrm{V}_{\text {DGR }}$ | $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}, \mathrm{R}_{\mathrm{GS}}=1 \mathrm{M} \Omega$ | 850 | V |
| $\mathrm{V}_{\text {GSS }}$ | Continuous | $\pm 30$ | V |
| $\mathrm{V}_{\text {GSM }}$ | Transient | $\pm 40$ | V |
| $\mathrm{I}_{\mathrm{D} 25}$ | $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | 3.5 | A |
| $\underline{I_{\text {D }}}$ | $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$, Pulse Width Limited by $\mathrm{T}_{\mathrm{JM}}$ | 10.0 | A |
| $\mathrm{I}_{\text {A }}$ | $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | 2 | A |
| $\mathrm{E}_{\text {AS }}$ | $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | 125 | mJ |
| dv/dt | $\mathrm{I}_{\mathrm{S}} \leq \mathrm{I}_{\mathrm{DM}}, \mathrm{V}_{\mathrm{DD}} \leq \mathrm{V}_{\text {DSS }}, \mathrm{T}_{\mathrm{J}} \leq 150^{\circ} \mathrm{C}$ | 50 | $\mathrm{V} / \mathrm{ns}$ |
| $\mathrm{P}_{\mathrm{D}}$ | $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | 150 | W |
| TJ |  | $-55 \ldots+150$ | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {JM }}$ |  | 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {stg }}$ |  | $-55 \ldots+150$ | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{L}}$ | Maximum Lead Temperature for Soldering | 300 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {sold }}$ | 1.6 mm (0.062in.) from Case for 10s | 260 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{F}_{\mathrm{c}}$ | Mounting Force (TO-263) | 10.. 65 / 2.2..14.6 | N/lb |
| $\mathrm{M}_{\mathrm{d}}$ | Mounting Torque (TO-220) | 1.13 / 10 | Nm/lb.in |
| Weight | TO-252 | 0.35 | g |
|  | TO-263 | 2.50 | g |
|  | TO-220 | 3.00 | g |


| Symbol Test Conditions$\left(T_{j}=25^{\circ} \mathrm{C}\right.$, Unless Otherwise Specified) |  | Characteristic Values |  |  |
| :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Typ. | Max. |
| $B V_{\text {DSs }}$ | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=250 \mu \mathrm{~A}$ | 850 |  | V |
| $\mathrm{V}_{\mathrm{GS}(\mathrm{th})}$ | $\mathrm{V}_{\mathrm{DS}}=\mathrm{V}_{\mathrm{GS}}, \mathrm{I}_{\mathrm{D}}=250 \mu \mathrm{~A}$ | 3.0 |  | 5.5 V |
| $\mathrm{I}_{\text {GSS }}$ | $\mathrm{V}_{\mathrm{GS}}= \pm 30 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=0 \mathrm{~V}$ |  |  | $\pm 100 \mathrm{nA}$ |
| $\mathrm{I}_{\text {DSS }}$ | $\mathrm{V}_{\mathrm{DS}}=\mathrm{V}_{\mathrm{DSS}}, \mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}$ |  |  | $5 \mu \mathrm{~A}$ $500 \mu \mathrm{~A}$ $500 \mu \mathrm{~A}$ |
| $\underline{\mathrm{R}_{\mathrm{DS} \text { (on) }}}$ | $V_{G S}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=2 \mathrm{~A}$, Note 1 |  |  | $2.5 \Omega$ |

$V_{\text {DSs }}=850 \mathrm{~V}$
$I_{D 25}=3.5 \mathrm{~A}$
$R_{D S(\text { on })} \leq 2.5 \Omega$

## TO-252 (IXFY)



TO-263 (IXFA)


TO-220 (IXFP)


G = Gate $\quad \mathrm{D}$ = Drain
$S=$ Source $\quad$ Tab $=$ Drain

## Features

- International Standard Packages
- Low $R_{\text {DS(ON) }}$ and $Q_{G}$
- Avalanche Rated
- Low Package Inductance


## Advantages

- High Power Density
- Easy to Mount
- Space Savings


## Applications

- Switch-Mode and Resonant-Mode

Power Supplies

- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls


Symbol Test Conditions

## Source-Drain Diode

| $\begin{aligned} & \text { Symbol } \quad \text { Test Conditions } \\ & \left(T_{J}=25^{\circ} \mathrm{C} \text {, Unless Otherwise Specified }\right) \\ & \hline \end{aligned}$ |  | Characteristic Values |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Typ. | Max |  |
| $\mathrm{I}_{\text {S }}$ | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}$ |  |  | 4 | A |
| $\mathrm{I}_{\text {SM }}$ | Repetitive, pulse Width Limited by $\mathrm{T}_{\mathrm{JM}}$ |  |  | 16 | A |
| $\mathrm{V}_{\text {sD }}$ | $\mathrm{I}_{\mathrm{F}}=\mathrm{I}_{\mathrm{S}}, \mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}$, Note 1 |  |  | 1.4 | V |
| $\begin{aligned} & \mathbf{t}_{\mathrm{rr}} \\ & \mathbf{Q}_{\mathrm{RM}} \\ & \mathbf{I}_{\mathrm{RM}} \end{aligned}$ | $\begin{aligned} & \mathrm{I}_{\mathrm{F}}=2 \mathrm{~A},-\mathrm{di} / \mathrm{dt}=100 \mathrm{~A} / \mu \mathrm{s} \\ & V_{R}=100 \mathrm{~V} \end{aligned}$ |  | 170 770 9 |  | ns nC A |

Note 1. Pulse test, $\mathrm{t} \leq 300 \mu \mathrm{~s}$, duty cycle, $\mathrm{d} \leq 2 \%$.

## PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

| IXYS MOSFETs and IGBTs are covered | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065B1 | 6,683,344 | 6,727,585 | 7,005,734B2 | 7,157,338B2 |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| by one or more of the following U.S. patents: | 4,860,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123B1 | 6,534,343 | 6,710,405B2 | 6,759,692 | 7,063,975B2 |  |
|  | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728B1 | 6,583,505 | 6,710,463 | 6,771,478B2 | 7,071,537 |  |

Fig. 1. Output Characteristics @ $\mathrm{T}_{\mathbf{J}}=\mathbf{2 5}{ }^{\circ} \mathrm{C}$


Fig. 3. Output Characteristics @ $\mathrm{T}_{\mathrm{J}}=125^{\circ} \mathrm{C}$


Fig. 5. R $_{\mathrm{DS}(\text { on })}$ Normalized to $\mathrm{I}_{\mathrm{D}}=2 \mathrm{~A}$ Value vs.
Drain Current


Fig. 2. Extended Output Characteristics @ $\mathbf{T}_{\mathbf{J}}=\mathbf{2 5}{ }^{\mathbf{\circ}} \mathrm{C}$


Fig. 4. $\mathrm{R}_{\mathrm{DS}(o n)}$ Normalized to $\mathrm{l}_{\mathrm{D}}=2 \mathrm{~A}$ Value vs. Junction Temperature


Fig. 6. Maximum Drain Current vs. Case Temperature


Fig. 7. Input Admittance


Fig. 9. Forward Voltage Drop of Intrinsic Diode


Fig. 11. Capacitance


Fig. 8. Transconductance


Fig. 10. Gate Charge


Fig. 12. Output Capacitance Stored Energy


IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

Fig. 13. Forward-Bias Safe Operating Area


Fig. 14. Maximum Transient Thermal Impedance



